

6AM15

Silicon N/P Channel MOS FET
High Speed Power Switching

HITACHI

ADE-208-719 (Z)

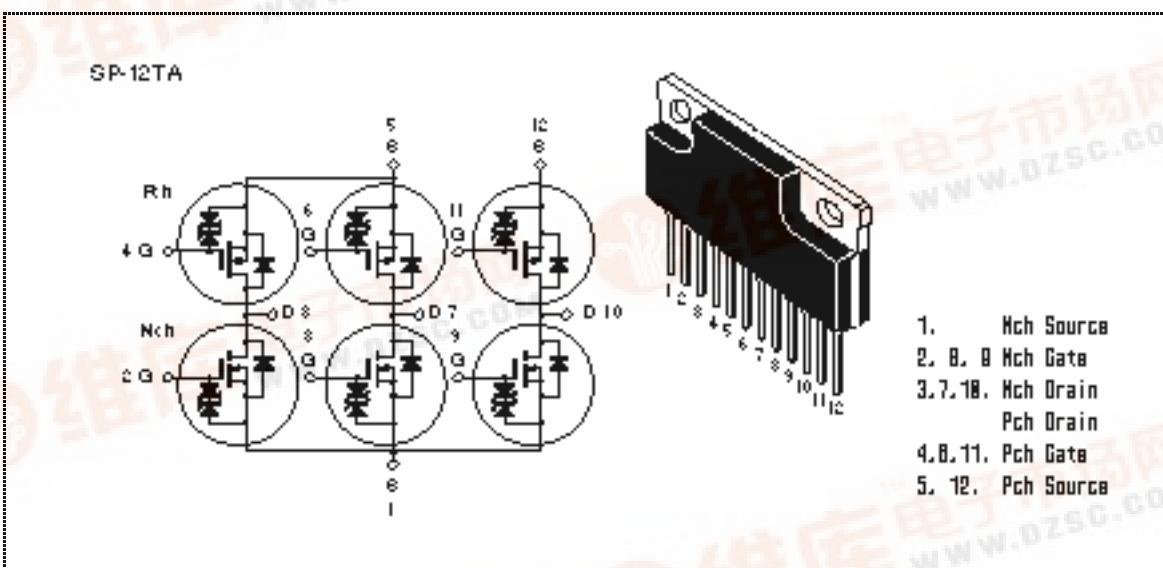
1st. Edition

February 1999

Features

- Low on-resistance
N Channel : $R_{DS(on)} = 0.045$ typ.
P Channel : $R_{DS(on)} = 0.085$ typ.
- High speed switching
- 4 V gate drive device can be driven from 5 V source
- High density mounting

Outline



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Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings		Unit
		Nch	Pch	
Drain to source voltage	V _{DSS}	60	-60	V
Gate to source voltage	V _{GSS}	±20	±20	V
Drain current	I _D	10	-10	A
Drain peak current	I _{D(pulse)}	Note1	40	A
Body-drain diode reverse drain current	I _{DR}	10	-10	A
Avalanche current	I _{AP}	Note3	10	A
Avalanche energy	E _{AR}	Note3	8.5	mJ
Channel dissipation	Pch (Tc = 25°C) Note2		42	W
Channel dissipation	Pch Note2		4.8	W
Channel temperature	T _{ch}	150		°C
Storage temperature	T _{stg}	-55 to +150		°C

Note: 1. PW 10 µs, duty cycle 1%
 2. 6 Devices operation
 3. Value at Ta = 25°C, R_g 50

Electrical Characteristics (N Channel) (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DS} S	60	—	—	V	I _D = 10 mA, V _{GS} = 0
Gate to source breakdown voltage	V _{(BR)GS} S	±20	—	—	V	I _G = ±100 µA, V _{DS} = 0
Gate to source leak current	I _{GSS}	—	—	±10	µA	V _{GS} = ±16 V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	10	µA	V _{DS} = 60 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	1.5	—	2.5	V	V _{DS} = 10 V, I _D = 1 mA
Static drain to source on state resistance	R _{D(on)}	—	0.045	0.060		I _D = 5 A, V _{GS} = 10 V Note5
Forward transfer admittance	y _{fs}	5.5	9	—	S	I _D = 5 A, V _{DS} = 10 V Note5
Input capacitance	C _{iss}	—	500	—	pF	V _{DS} = 10 V
Output capacitance	C _{oss}	—	260	—	pF	V _{GS} = 0
Reverse transfer capacitance	C _{rss}	—	110	—	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	—	10	—	ns	V _{GS} = 10 V, I _D = 5 A

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Rise time	t_r	—	50	—	ns	$R_L = 6$
Turn-off delay time	$t_d(\text{off})$	—	90	—	ns	
Fall time	t_f	—	100	—	ns	
Body-drain diode forward voltage	V_{DF}	—	0.9	—	V	$I_F = 10 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t_{rr}	—	52	—	ns	$I_F = 10 \text{ A}, V_{GS} = 0$ $dI/F/dt = 50 \text{ A}/\mu\text{s}$

Note: 5. Pulse test

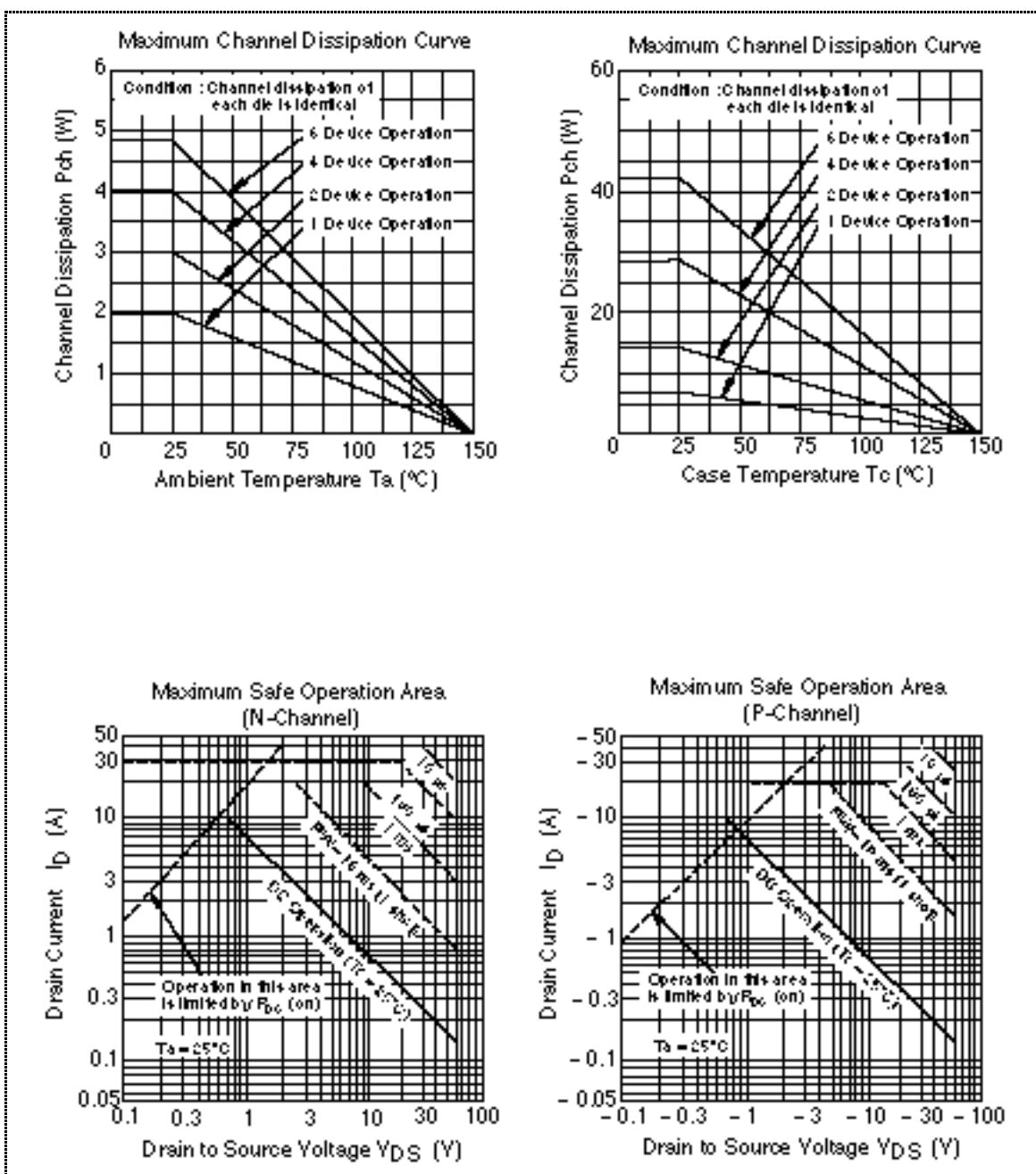
Electrical Characteristics (P Channel) ($T_a = 25^\circ\text{C}$)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DS}$ S	-60	—	—	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GS}$ S	± 20	—	—	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	-10	μA	$V_{DS} = -60 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(\text{off})}$	-1.0	—	-2.0	V	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$
Static drain to source on state resistance	$R_{DS(\text{on})}$	—	0.085	0.105		$I_D = -5 \text{ A}, V_{GS} = -10 \text{ V}$ Note5
resistance	$R_{DS(\text{on})}$	—	0.115	0.165		$I_D = -5 \text{ A}, V_{GS} = -4 \text{ V}$ Note5
Forward transfer admittance	$ y_{fs} $	5.5	9	—	S	$I_D = -5 \text{ A}, V_{DS} = -10 \text{ V}$ Note5
Input capacitance	C_{iss}	—	850	—	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	C_{oss}	—	420	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	110	—	pF	$f = 1 \text{ MHz}$
Turn-on delay time	$t_d(\text{on})$	—	12	—	ns	$V_{GS} = -10 \text{ V}, I_D = -5 \text{ A}$
Rise time	t_r	—	55	—	ns	$R_L = 6$
Turn-off delay time	$t_d(\text{off})$	—	130	—	ns	
Fall time	t_f	—	70	—	ns	
Body-drain diode forward voltage	V_{DF}	—	-0.95	—	V	$I_F = -10 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t_{rr}	—	65	—	ns	$I_F = -10 \text{ A}, V_{GS} = 0$ $dI/F/dt = 50 \text{ A}/\mu\text{s}$

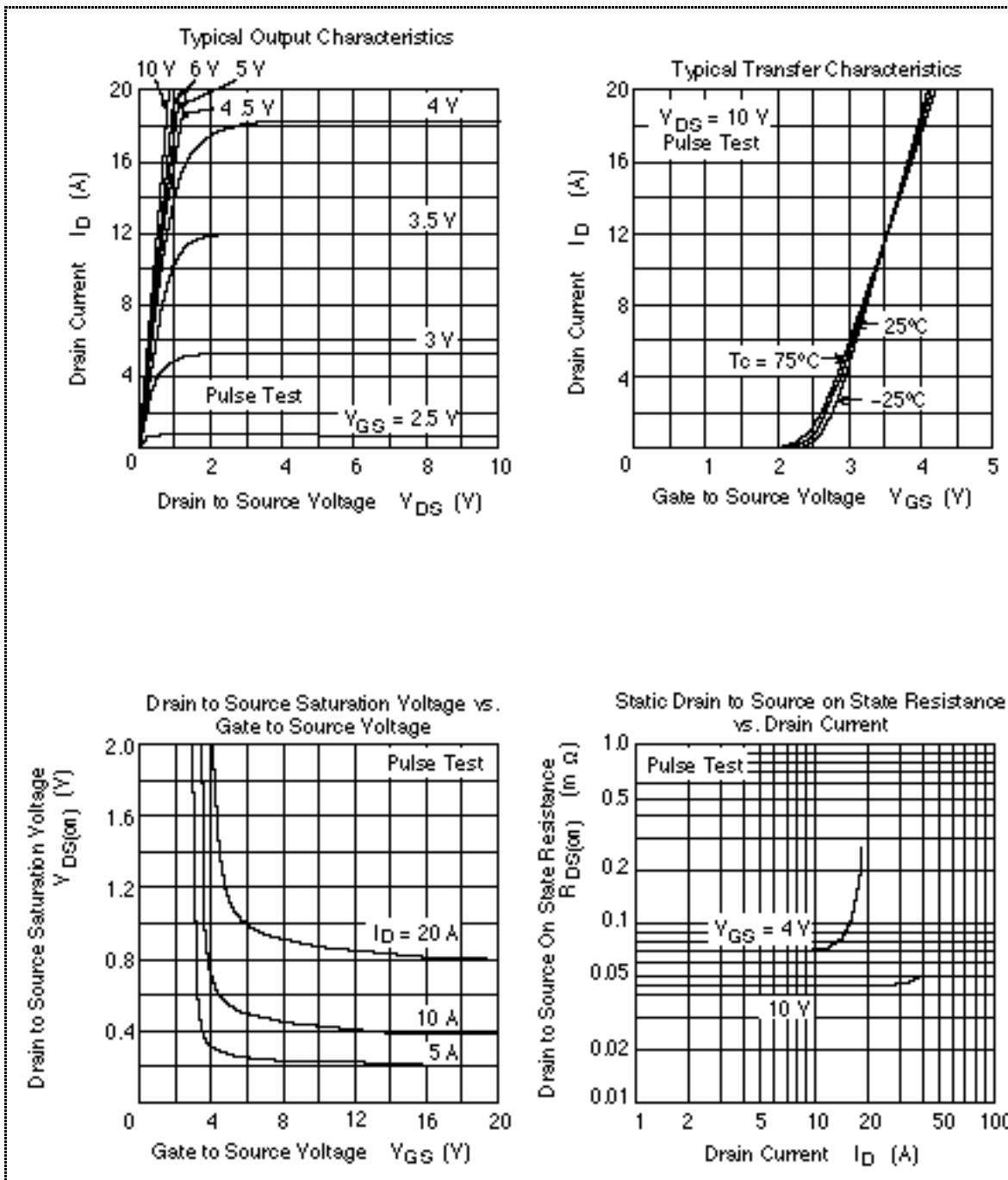
Note: 5. Pulse test

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Main Characteristics

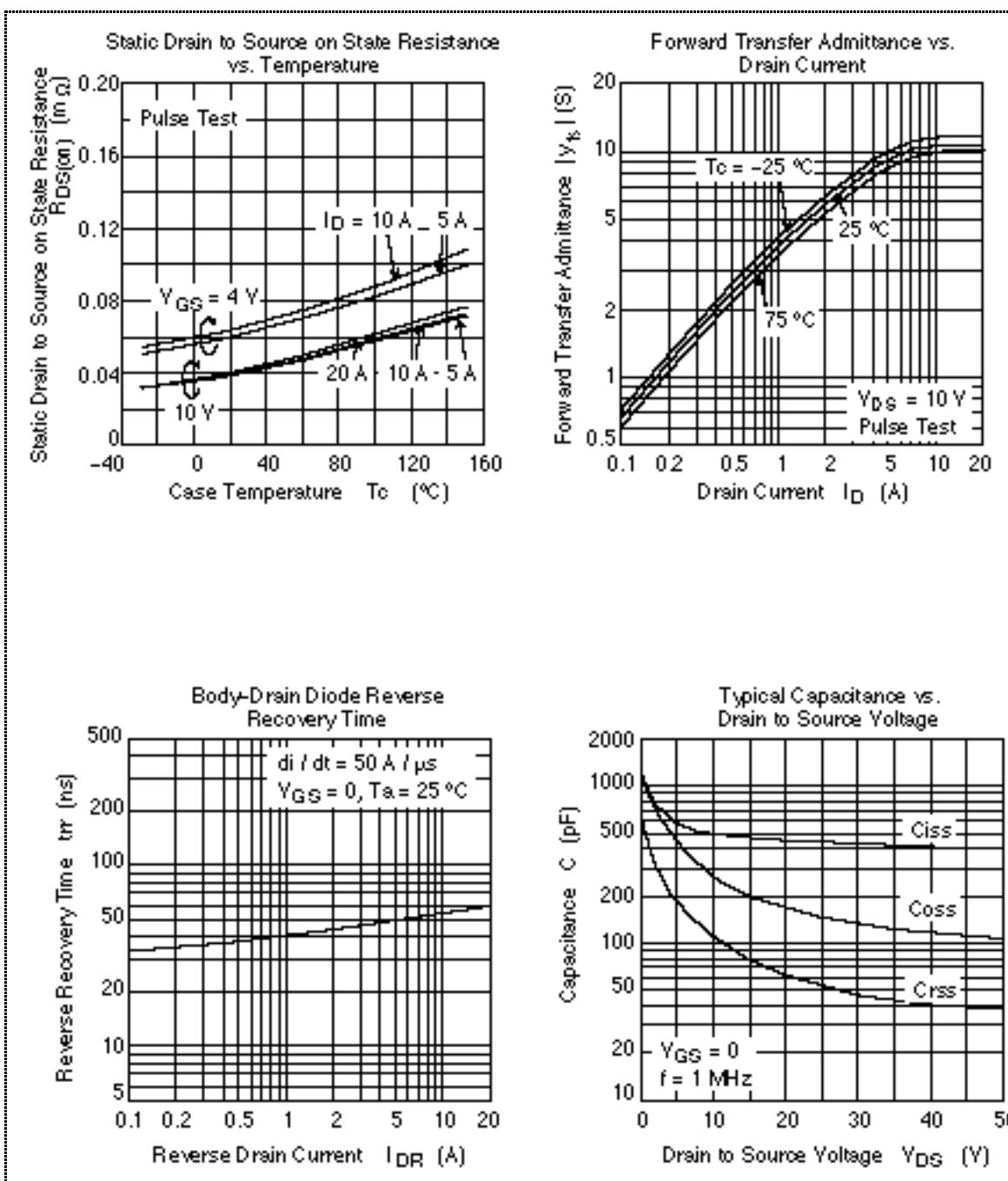


Main Characteristics (N Channel)

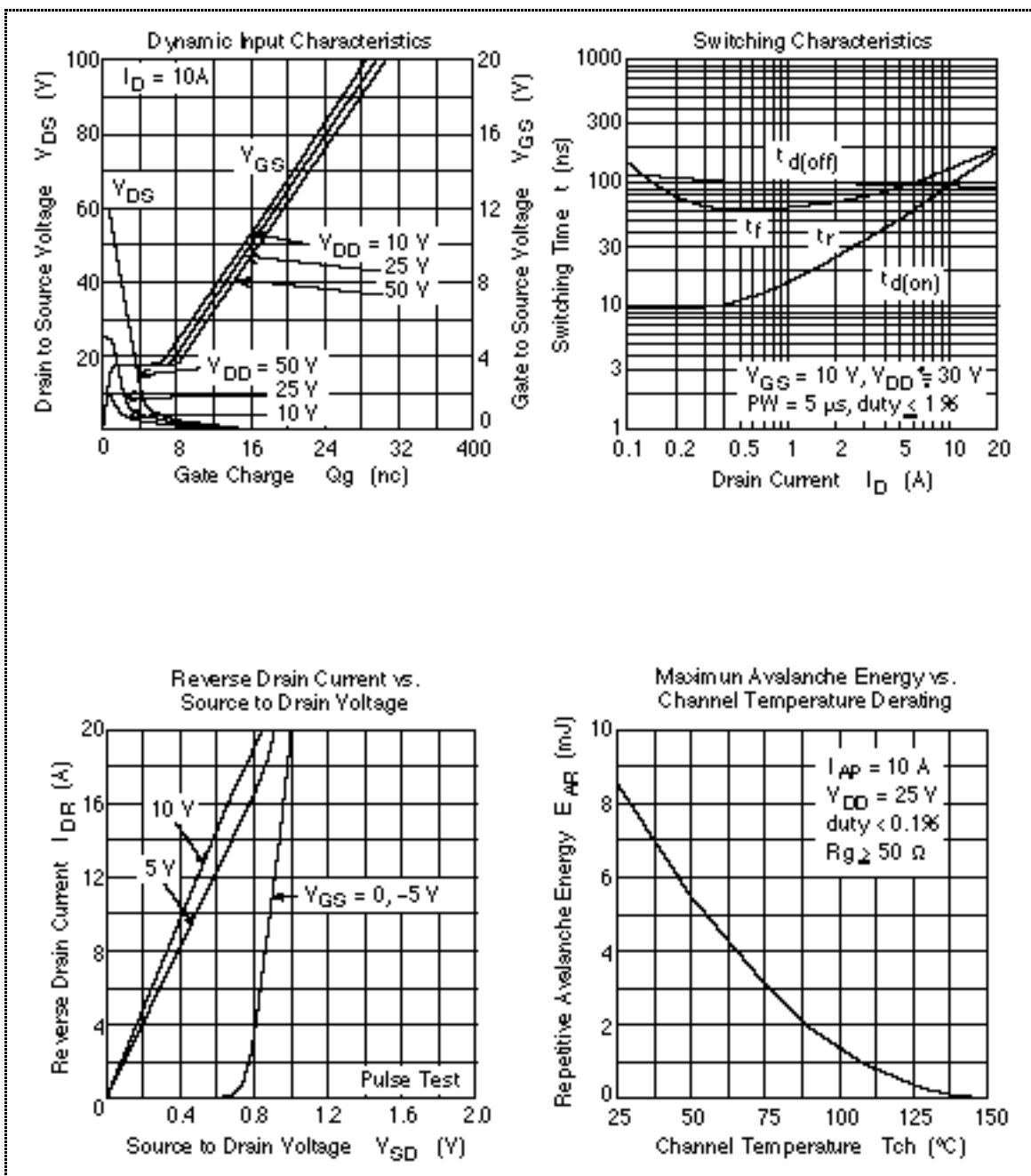


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Main Characteristics (N Channel)

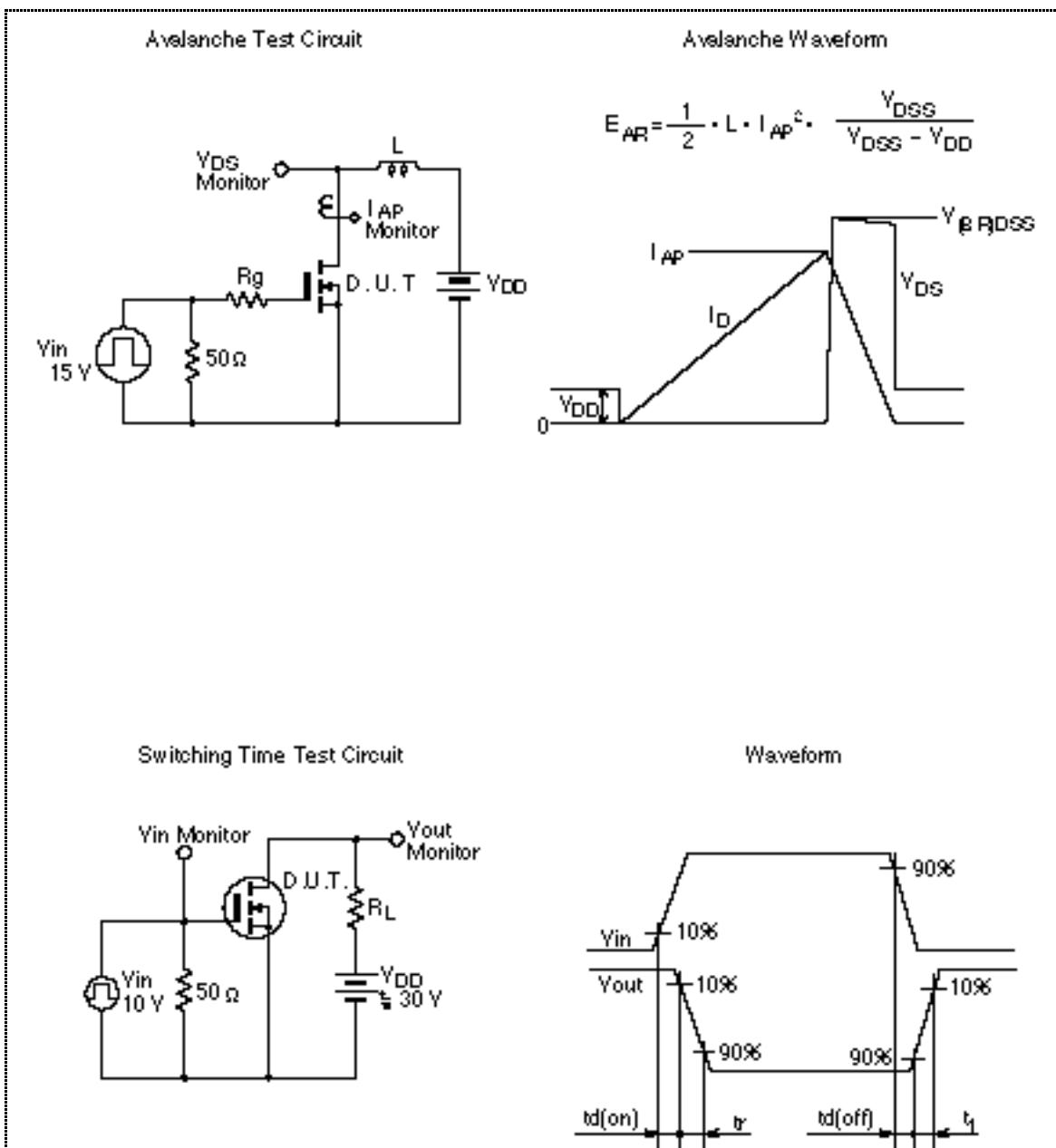


Main Characteristics (N Channel)

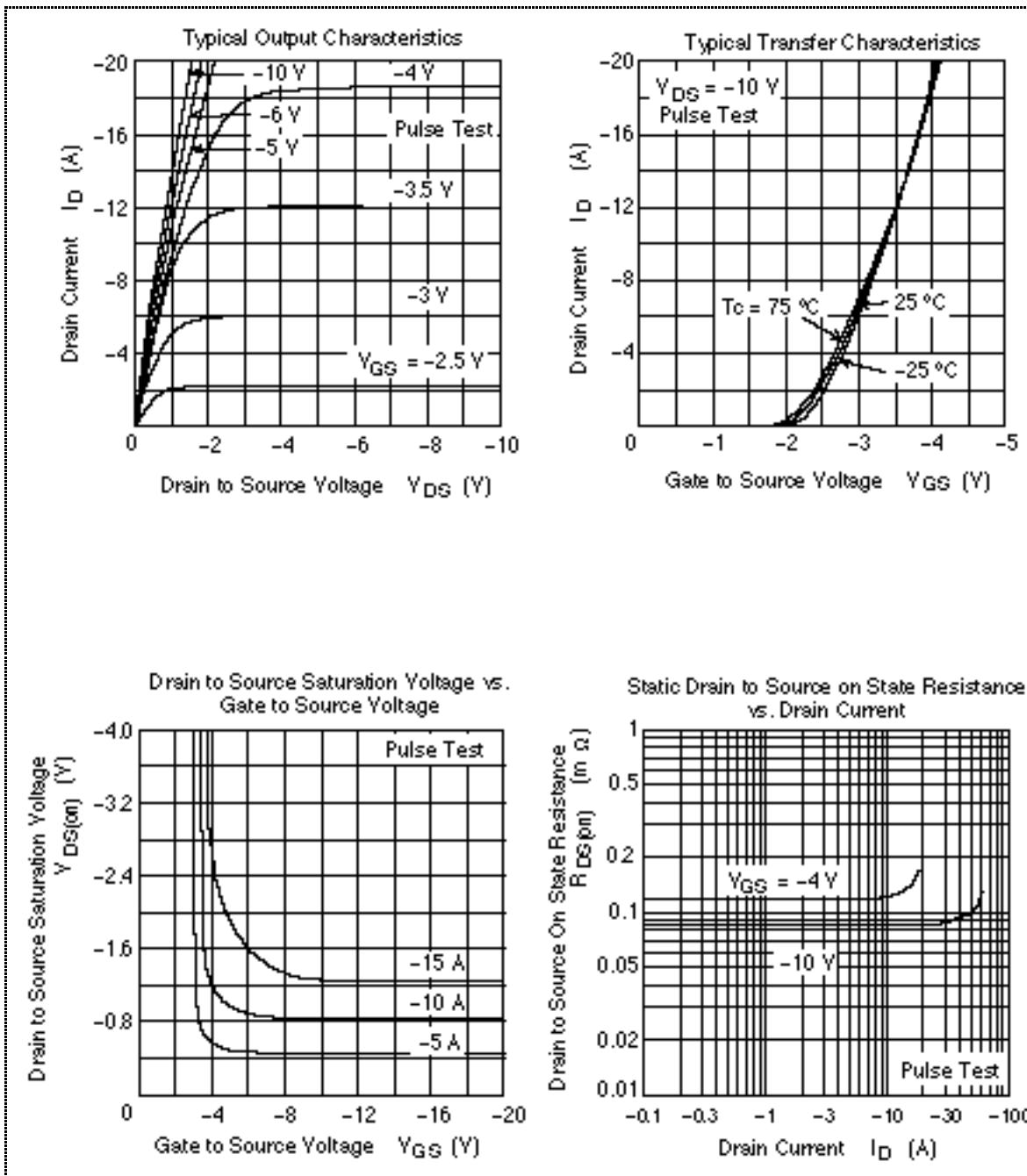


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Main Characteristics (N Channel)

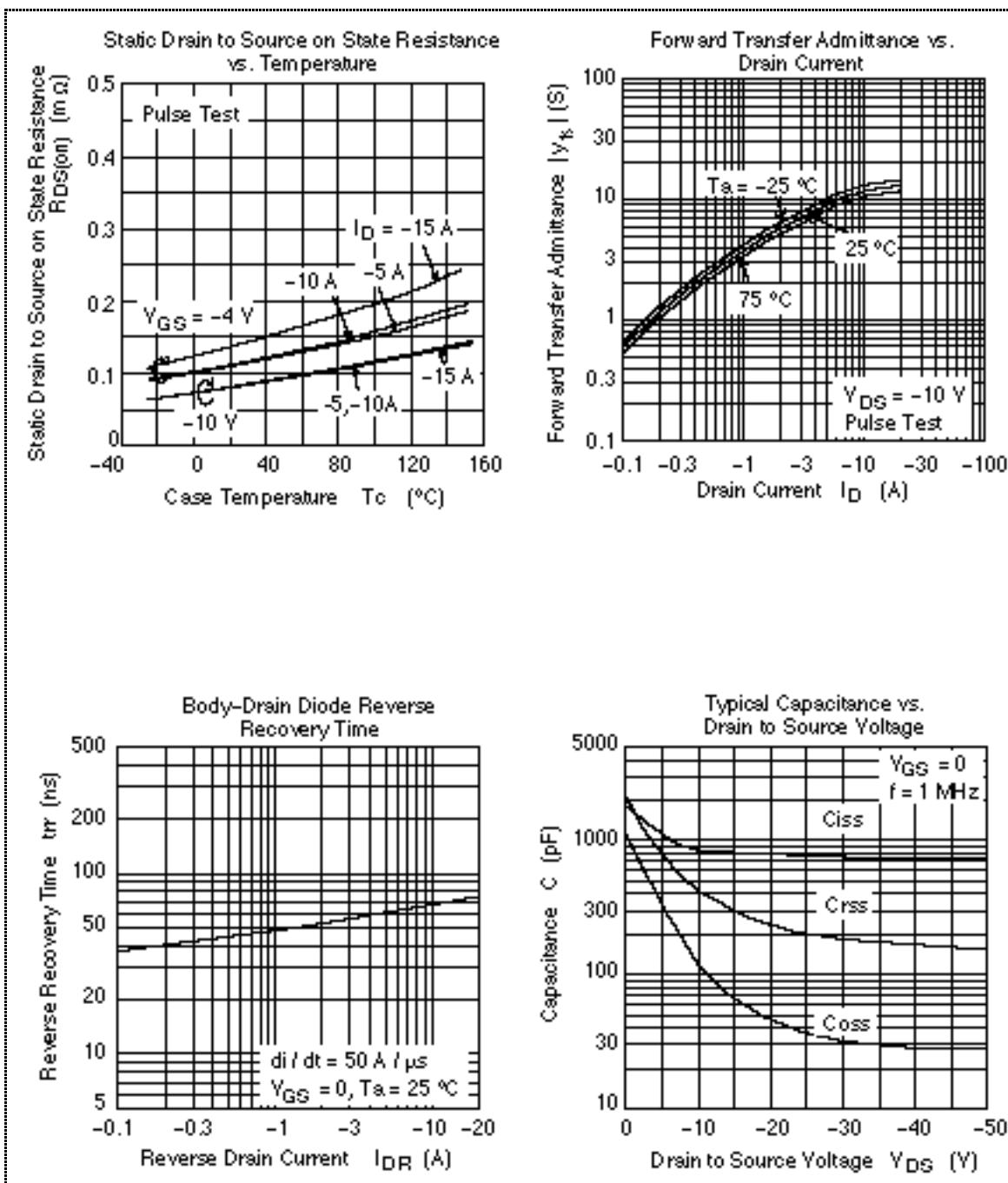


Main Characteristics (P Channel)

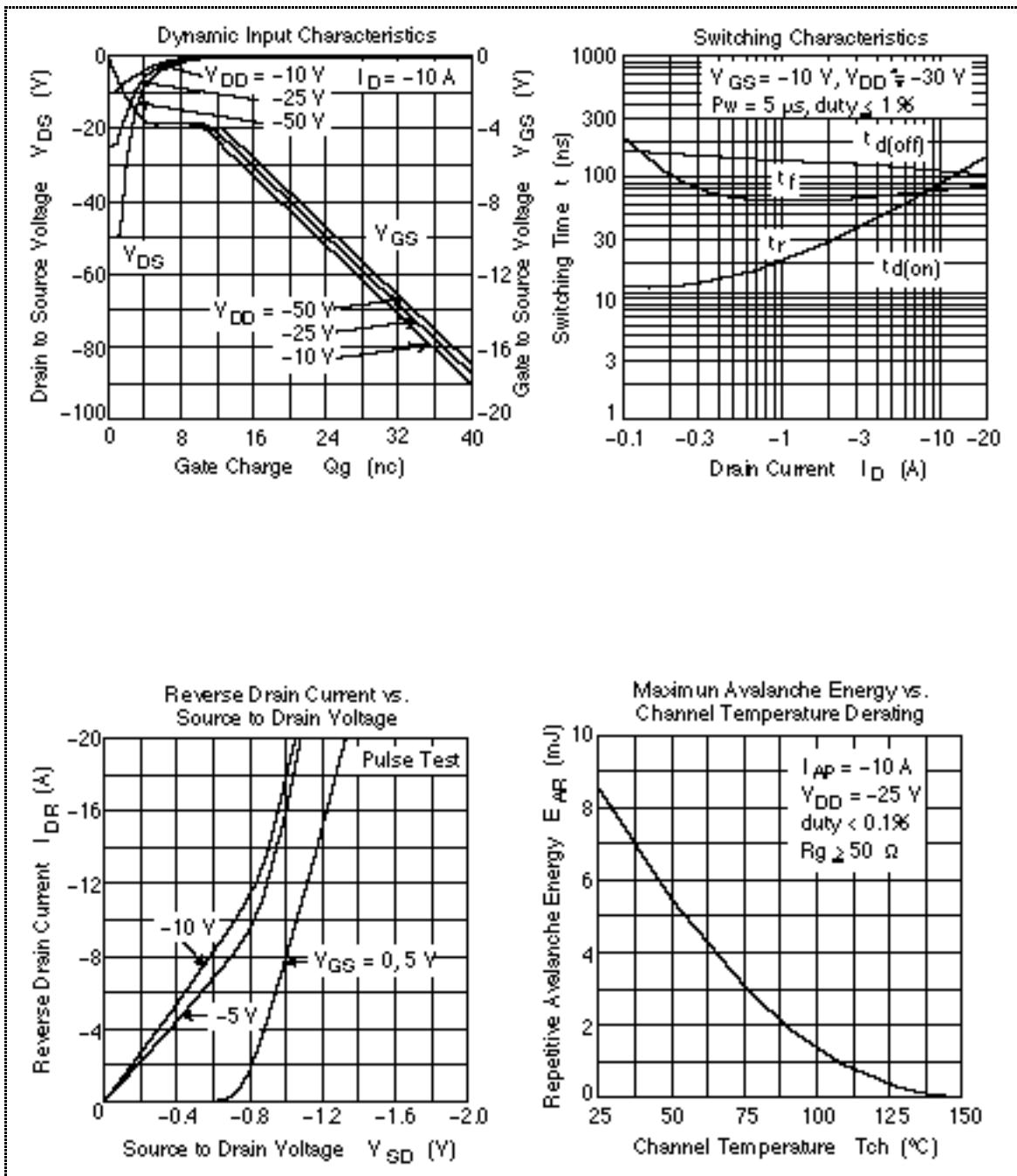


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Main Characteristics (P Channel)

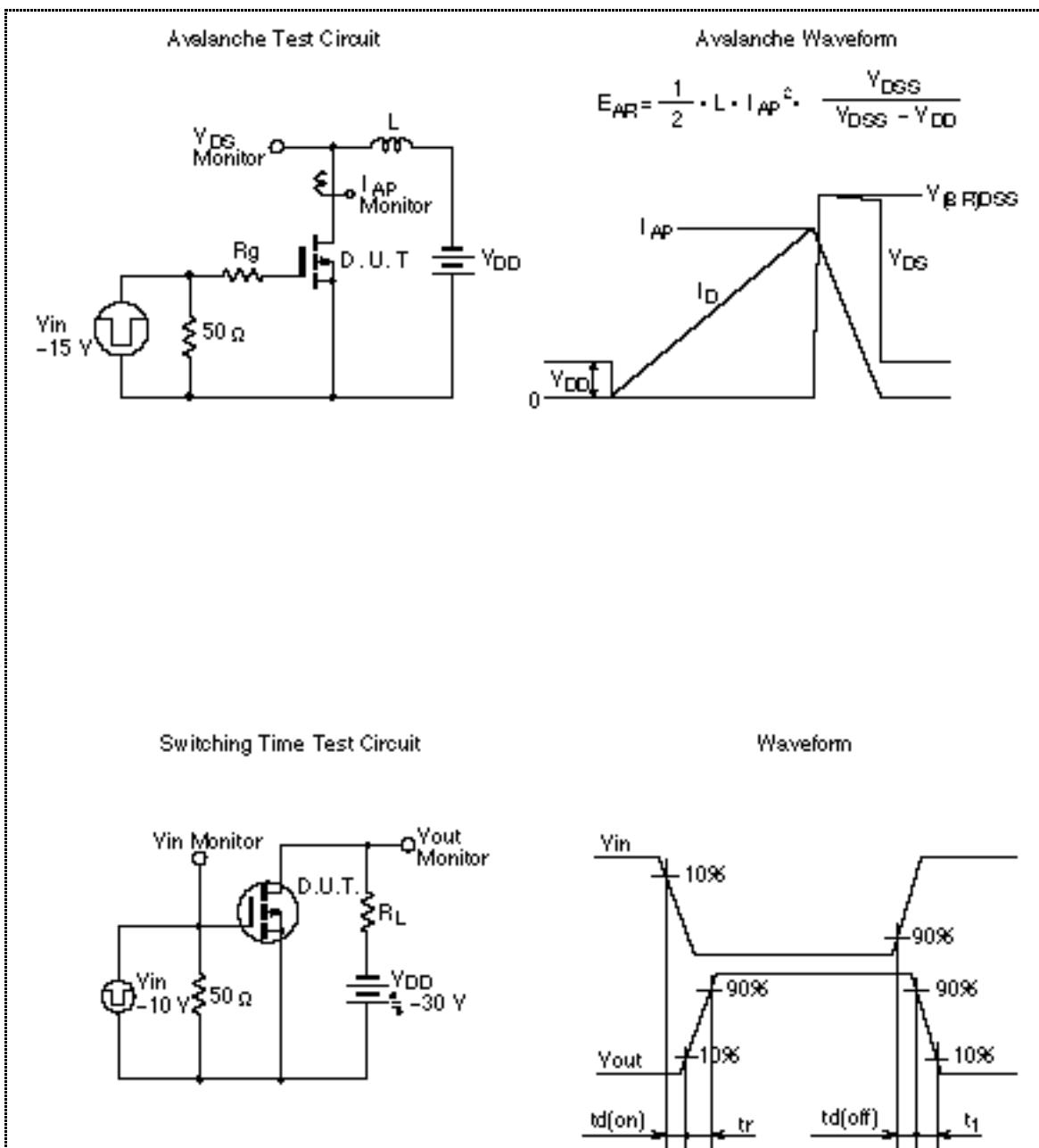


Main Characteristics (P Channel)



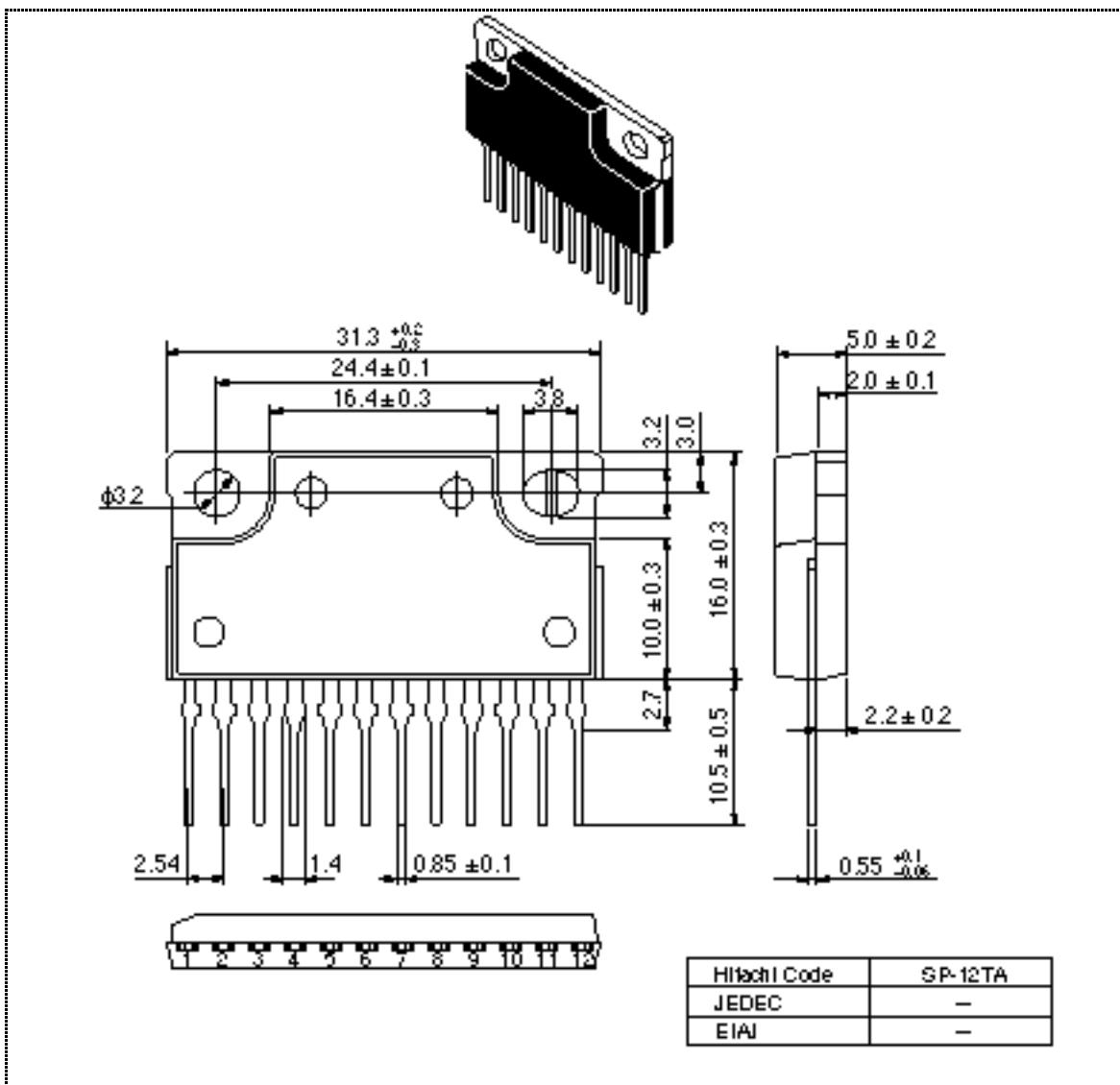
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Main Characteristics (P Channel)



Package Dimensions

Unit: mm



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